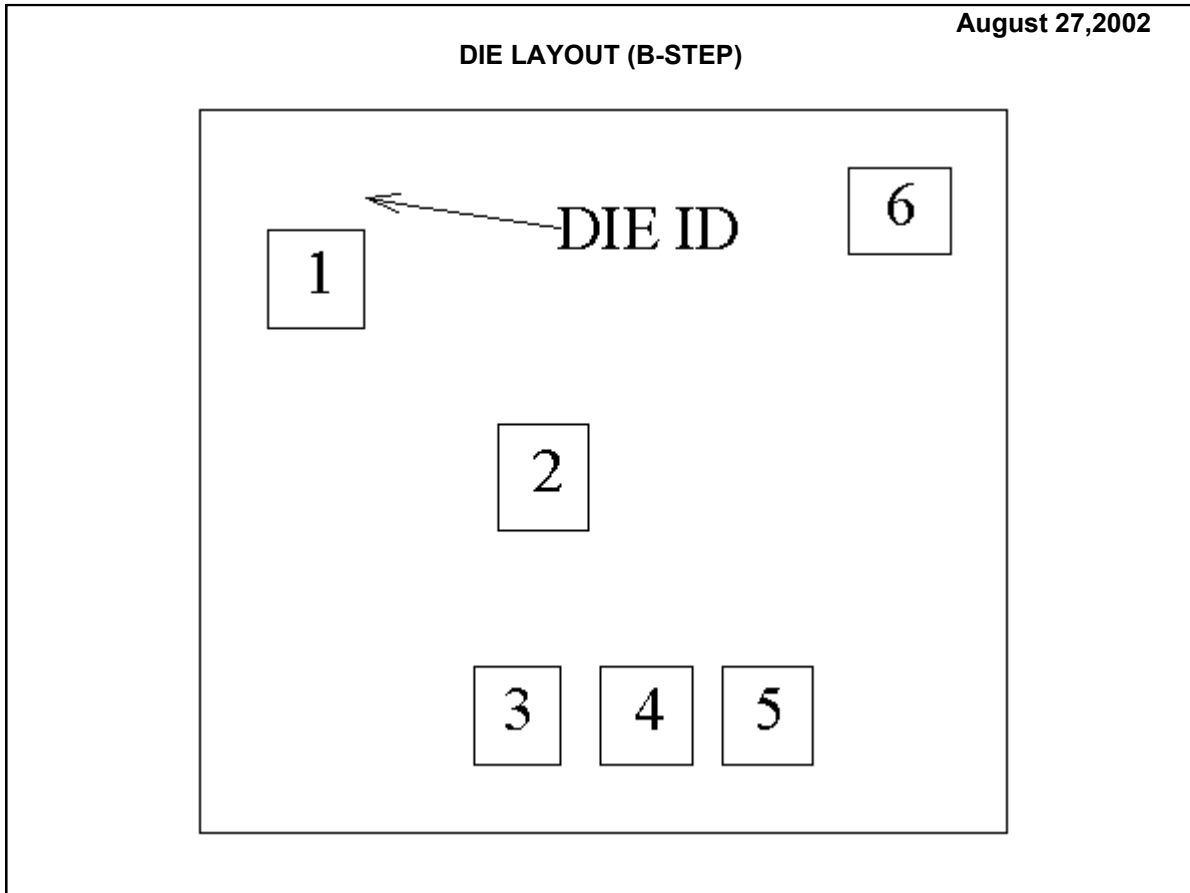


**LM134 MDC MWC
3-TERMINAL ADJUSTABLE CURRENT SOURCE**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	134B	Bond Pad Opening Size (min)	104 μ m x 117 μ m
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	965 μ m x 864 μ m 38mils x 34mils	Back Side Connection	V-
Thickness	406 μ m Nominal		
Min Pitch	143 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

LM134 MDC MWC

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Die Bond Pad Coordinate Locations (B -Step)							
(Referenced to die center, coordinates in μm) NC = No Connection							
SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		X	Y
		X	Y	X	Y		
V+	1	-343	229	117	x	117	
NC	2	-71	-8	107	x	127	
V-	3	-103	-292	104	x	117	
NC	4	52	-292	109	x	117	
NC	5	196	-292	107	x	117	
R	6	353	311	122	x	104	

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IN U.S.A.

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Fax: 1 207 541 6140

IN EUROPE

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Fax: 49 (0) 8141 351470

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